

High Speed Optocoupler, 10 MBd



ANODE 2 CATHODE 3 6 NC 4 AL CAL US COVE

DESCRIPTION

The VOWH260A is a single channel 10 MBd optocoupler utilizing a high efficient input LED coupled to a high speed integrated photo-detector logic gate with a strobable output. This detector features an open drain output. The internal shield provides a guaranteed common mode transient immunity of 15 kV/µs.

The high isolation distance of > 10 mm makes the part ideal for applications with working voltages exceeding 1000 V.

FEATURES

- CMTI of 15 kV/µs (min.)
- 3.3 V / 5 V dual supply voltage
- LVTTL/LVCMOS compatibility
- Low power consumption
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912







APPLICATIONS

- Microprocessor system interface
- · Ground loop elimination
- · Digital bus systems isolation
- High speed A/D and D/A conversion
- · Digital control power supply
- Level shifting

AGENCY APPROVALS

- <u>UL1577</u>
- cUL
- DIN EN 60747-5-5 (VDE 0884-5), available with option 1

LINKS TO ADDITIONAL RESOURCES













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ORDERING INFORMATION	
V O W H	2 6 0 A - X 0 # # T
PART	NUMBER PACKAGE OPTION TAPE AND REEL
AGENCY CERTIFIED / PACKAGE	
UL, cUL	
DIP-8, 400 mil, widebody	VOWH260A
SMD-8, 400 mil, widebody (option 7)	VOWH260A-X007T
UL, cUL, VDE (option 1)	
DIP-8, 400 mil, widebody	VOWH260A-X001
SMD-8, 400 mil, widebody (option 7)	VOWH260A-X017T

Note

· Additional options may be possible, please contact sales office

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT	•		<u>.</u>	
Input forward current		I _F	20	mA
Reverse input voltage		V _R	5	V
Enable input voltage		V _E	V _{CC} + 0.5 V	V
Enable input current		I _E	5	mA
Input power dissipation		P _{diss}	40	mW
OUTPUT				
Supply voltage		V _{CC}	7	V
Output current		Io	50	mA
Output voltage		Vo	7	V
Output power dissipation		P _{diss}	85	mW
COUPLER				
Storage temperature		T _{stg}	-55 to +125	°C
Operating temperature		T _{amb}	-40 to +110	°C
Solder reflow temperature (1)	5 s		260	°C

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not
 implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute
 maximum ratings for extended periods of the time can adversely affect reliability
- (1) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP)



RECOMMENDED OPERATING CONDITIONS					
PARAMETER	SYMBOL	MIN.	MAX.	UNIT	
Operating temperature	T _{amb}	-40	+110	°C	
Supply voltage	V _{CC}	2.7	3.6	V	
Supply voltage	V _{CC}	4.5	5.5	V	
Input current low level	I _{FL}	0	250	μΑ	
Input current high level	I _{FH}	5	15	mA	
Logic low enable voltage	V_{EL}	0	0.8	V	
Logic high enable voltage	V _{EH}	2	V_{CC}	V	
Output pull up resistor	R_L	330	4000	Ω	
Fanout ($R_L = 1 \text{ k}\Omega$)	N	-	5	TTL loads	

TRUTH TABLE (positive logic)				
LED	ENABLE	OUTPUT		
On	Н	L		
Off	Н	Н		
On	L	Н		
Off	L	Н		
On	Not connected / open	L		
Off	Not connected / open	Н		

ELECTRICAL CHARACTERSITCS ($T_{amb} = -40 ^{\circ}\text{C}$ to +110 $^{\circ}\text{C}$, 2.7 V \leq V _{CC} \leq 3.6 V,						
$I_F = 7.5$ mA, unless otherwise	se specified; typical values are a	at $V_{CC} = 3.3$	$3 V, T_{amb} =$	25 °C)		
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Input forward voltage	I _F = 10 mA	V_{F}	ı	1.38	1.70	V
Input forward voltage temperature coefficient	I _F = 10 mA	$\Delta V_F/\Delta T$	-	-1.5	-	mV/K
Input reverse voltage	I _R = 10 μA	BV_R	5	-	-	V
Input threshold current	$V_E = 2 \text{ V}, V_O = 0.6 \text{ V}, V_{CC} = 3.3 \text{ V}, \\ I_{OL} \text{ (sinking)} = 13 \text{ mA}$	I _{TH}	-	2	5	mA
Input capacitance	f = 1 MHz, V _F = 0 V	C _I	-	34	-	pF
OUTPUT						
Low level supply current	$I_F = 10 \text{ mA}, V_{CC} = 3.3 \text{ V}, V_E = 0.5 \text{ V}$	I _{CCL}	1	3.1	5	mA
High level supply current	$I_F = 0 \text{ mA}, V_{CC} = 3.3 \text{ V}, V_E = 0.5 \text{ V}$	I _{CCH}	-	3.3	5	mA
Low level enable current	$V_{CC} = 3.3 \text{ V}, V_{E} = 0.5 \text{ V}$	I _{EL}	ı	-0.41	-1.6	mA
High level enable current	$V_{CC} = 3.3 \text{ V}, V_{E} = 2 \text{ V}$	I _{EH}	1	-0.19	-1.6	mA
Low level enable voltage		V_{EL}	-	-	0.8	V
High level enable voltage		V_{EH}	2	-	-	V
Low level output voltage	$V_{CC} = 3.3 \text{ V}, V_E = 2 \text{ V}, I_F = 5 \text{ mA}, I_{OL} \text{ (sinking)} = 13 \text{ mA}$	V _{OL}	-	0.2	0.6	V
High level output current	$V_{CC} = 3.3 \text{ V}, V_E = 2 \text{ V}, V_O = 3.3 \text{ V},$ $I_F = 250 \mu\text{A}$	I _{OH}	-	1	10	μA
COUPLER						
Input to output capacitance	f = 1 MHz, T _{amb} = 25 °C	C _{IO}	-	1	-	pF

Note

• Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements



ELECTRICAL CHARACTERSITCS (T_{amb} = -40 °C to +110 °C, 4.5 V \leq V _{CC} \leq 5.5 V, I_{F} = 7.5 mA, unless otherwise specified; typical values are at V _{CC} = 5.0 V, T_{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Input forward voltage	I _F = 10 mA	V_{F}	-	1.38	1.70	V
Input forward voltage temperature coefficient	I _F = 10 mA	$\Delta V_F/\Delta T$	-	-1.5	-	mV/K
Input reverse voltage	I _R = 10 μA	BV _R	5	=.	=	V
Input threshold current	$V_E = 2 \text{ V}, V_O = 0.6 \text{ V}, V_{CC} = 5.5 \text{ V},$ I_{OL} (sinking) = 13 mA	I _{TH}	-	2	5	mA
Input capacitance	f = 1 MHz, V _F = 0 V	C _I	-	34	-	pF
OUTPUT						
Low level supply current	$I_F = 10 \text{ mA}, V_{CC} = 5.5 \text{ V}, V_E = 0.5 \text{ V}$	I _{CCL}	-	3.5	5	mA
High level supply current	$I_F = 0 \text{ mA}, V_{CC} = 5.5 \text{ V}, V_E = 0.5 \text{ V}$	I _{CCH}	-	3.7	5	mA
Low level enable current	$V_{CC} = 5.5 \text{ V}, V_{E} = 0.5 \text{ V}$	I _{EL}	-	-0.9	-1.6	mA
High level enable current	$V_{CC} = 5.5 \text{ V}, V_{E} = 2 \text{ V}$	I _{EH}	-	-0.6	-1.6	mA
Low level enable voltage		V _{EL}	-	-	0.8	V
High level enable voltage		V_{EH}	2	-	-	V
Low level output voltage	$V_{CC} = 5.5 \text{ V}, V_E = 2 \text{ V}, I_F = 5 \text{ mA}, I_{OL} \text{ (sinking)} = 13 \text{ mA}$	V _{OL}	-	0.20	0.60	V
High level output current	$V_{CC} = 5.5 \text{ V}, V_E = 2 \text{ V}, V_O = 5.5 \text{ V},$ $I_F = 250 \mu\text{A}$	Іон	-	1	10	μА
COUPLER						
Input to output capacitance	f = 1 MHz, T _{amb} = 25 °C	C _{IO}	1	1	-	pF

Note

 Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements

SWITCHING CHARACTERISTICS (T_{amb} = -40 °C to +110 °C, 2.7 V \leq V _{CC} \leq 3.6 V, I_{F} = 7.5 mA, unless otherwise specified; typical values are at V _{CC} = 3.3 V, T_{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to high output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH}	25	50	90	ns
Propagation delay time to low output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PHL}	25	40	90	ns
Pulse width distortion	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH} - t _{PHL}	-	10	-	ns
Propagation delay skew	$R_L = 350 \Omega, C_L = 15 pF$	t _{PSK}	-	-	40	ns
Output rise time (10 % to 90 %)	$R_L = 350 \Omega$, $C_L = 15 pF$	t _r	-	23	-	ns
Output fall time (90 % to 10 %)	$R_L = 350 \Omega$, $C_L = 15 pF$	t _f	-	10	-	ns
Propagation delay time of enable from V _{EH} to V _{EL}	$R_L = 350 \Omega, C_L = 15 pF,$ $V_{EL} = 0 V, V_{EH} = 3 V$	t _{ELH}	-	15	-	ns
Propagation delay time of enable from V _{EL} to V _{EH}	$R_L = 350 \Omega, C_L = 15 pF,$ $V_{EL} = 0 V, V_{EH} = 3 V$	t _{EHL}	-	15	-	ns



SWITCHING CHARACTERISTICS ($T_{amb} = -40 ^{\circ}\text{C}$ to +110 $^{\circ}\text{C}$, 4.5 V \leq V _{CC} \leq 5.5 V, $I_{F} = 7.5 \text{mA}$, unless otherwise specified; typical values are at V _{CC} = 5.0 V, $T_{amb} = 25 ^{\circ}\text{C}$)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to	$R_L = 350 \Omega$, $C_L = 15 pF$, $T_{amb} = 25 °C$	t _{PLH}	25	50	90	ns
high output level	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH}	-	=	100	ns
Propagation delay time to	$R_L = 350 \Omega$, $C_L = 15 pF$, $T_{amb} = 25 °C$	t _{PHL}	25	40	90	ns
low output level	$R_L = 350 \Omega$, $C_L = 15 pF$	t _{PHL}	-	-	100	ns
Pulse width distortion	$R_L = 350 \Omega, C_L = 15 pF$	t _{PLH} - t _{PHL}	-	10	-	ns
Propagation delay skew	$R_L = 350 \Omega, C_L = 15 pF$	t _{PSK}	-	=	40	ns
Output rise time (10 % to 90 %)	$R_L = 350 \Omega, C_L = 15 pF$	t _r	-	23	-	ns
Output fall time (90 % to 10 %)	$R_L = 350 \Omega, C_L = 15 pF$	t _f	-	10	-	ns
Propagation delay time of enable from V _{EH} to V _{EL}	$R_L = 350 \ \Omega, \ C_L = 15 \ pF, \ V_{EL} = 0 \ V, \ V_{EH} = 3 \ V$	t _{ELH}	-	15	-	ns
Propagation delay time of enable from V _{EL} to V _{EH}	$R_L = 350 \ \Omega, \ C_L = 15 \ pF, \ V_{EL} = 0 \ V, \ V_{EH} = 3 \ V$	t _{EHL}	-	15	-	ns

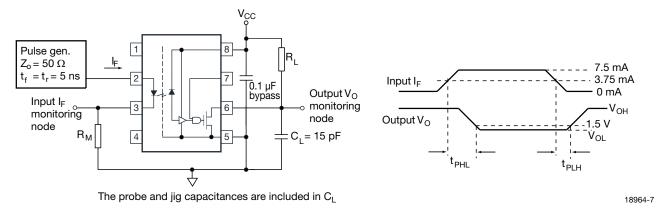


Fig. 1 - Test Circuit for $t_{PLH},\,t_{PHL},\,t_{r},$ and t_{f}

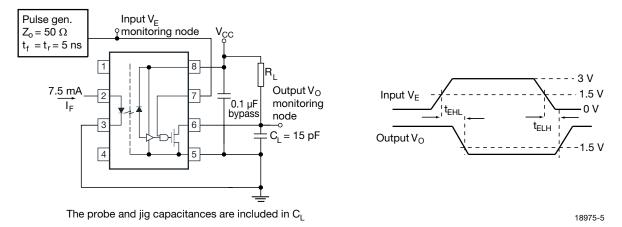


Fig. 2 - Test Circuit for $t_{\text{EHL}},$ and t_{ELH}



COMMON MODE TRANSIENT IMMUNITY (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	TEST CONDITION SYMBOL MIN.			MAX.	UNIT
Logic high common mode	$\begin{split} V_{CC} = 3.3 \text{ V, } V_{CM} &= 1000 \text{ V, } I_F = 0 \text{ mA,} \\ V_O > 2.0 \text{ V, } R_L = 350 \Omega \end{split}$	CM _H	15 000	-	-	V/µs
transient immunity	$\begin{split} V_{CC} = 5 \text{ V}, & V_{CM} = 1000 \text{ V}, I_F = 0 \text{ mA}, \\ & V_O > 2.0 \text{ V}, R_L = 350 \Omega \end{split}$	CM _H	15 000	-	ı	V/µs
Logic low common mode	$\begin{split} V_{CC} = 5 \text{ V, } V_{CM} = 1000 \text{ V, } I_F = 10 \text{ mA,} \\ V_O < 0.8 \text{ V, } R_L = 350 \Omega \end{split}$	CM _L	15 000	-	ı	V/µs
transient immunity	$V_{CC} = 5 \text{ V}, \ V_{CM} = 1000 \text{ V}, \ I_F = 10 \text{ mA}, \\ V_O < 0.8 \text{ V}, \ R_L = 350 \ \Omega$	CM _L	15 000	-	-	V/µs

Notes

• No external pull up is required for a high logic state on the enable input. If the enable pin in not used, connect it to V_{CC}

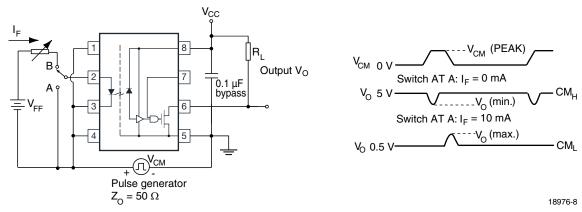


Fig. 3 - Test Circuit for Common Mode Transient Immunity

SAFETY AND INSULATION RATINGS						
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT		
Climatic classification	According to IEC 68 part 1		55 / 110 / 21			
Pollution degree	According to DIN VDE 0109		2			
Comparative tracking index	Insulation group IIIa	CTI	175			
Maximum rated withstanding isolation voltage	According to UL1577, t = 1 min	V _{ISO}	5000	V _{RMS}		
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V _{IOTM}	8000	V _{peak}		
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V _{IORM}	1414	V _{peak}		
Isolation resistance	$T_{amb} = 25 ^{\circ}C, V_{IO} = 500 V$	R _{IO}	≥ 10 ¹²	Ω		
Maximum output power dissipation		P _{SO}	600	mW		
Maximum input current		I _{SI}	230	mA		
Maximum ambient temperature (derated)		T _S	175	°C		
Creepage distance			≥ 10	mm		
Clearance distance			≥ 10	mm		
Insulation thickness		DTI	≥ 0.4	mm		

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

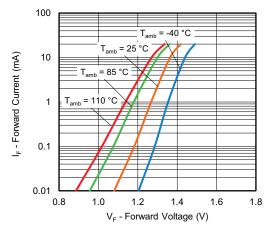
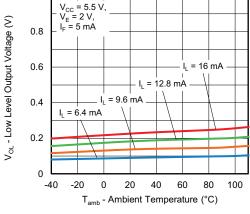


Fig. 4 - Diode Forward Current vs. Forward Voltage



1.0

Fig. 7 - Low Level Output Voltage vs. Ambient Temperature

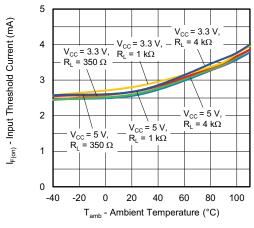


Fig. 5 - Input Threshold Current vs. Ambient Temperature

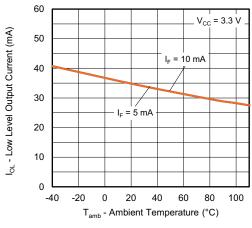


Fig. 8 - Low Level Output Current vs. Ambient Temperature

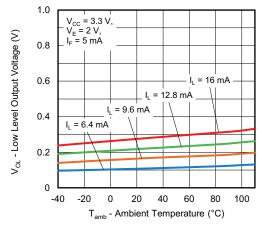


Fig. 6 - Low Level Output Voltage vs. Ambient Temperature

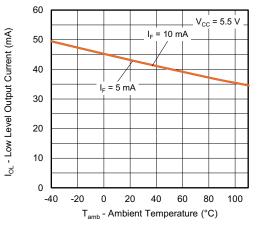


Fig. 9 - Low Level Output Current vs. Ambient Temperature

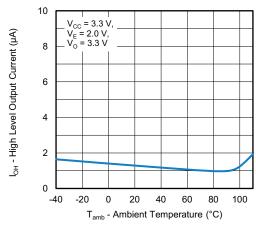


Fig. 10 - High Level Output Current vs. Ambient Temperature

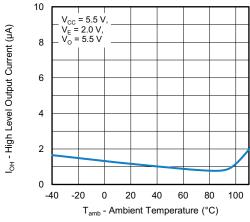


Fig. 11 - High Level Output Current vs. Ambient Temperature

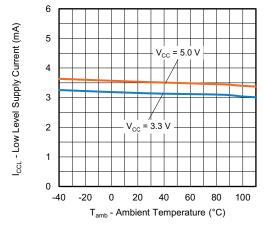


Fig. 12 - Low Level Supply Current vs. Ambient Temperature

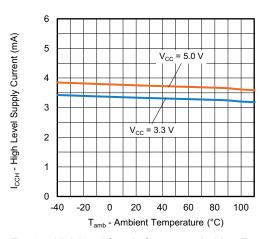


Fig. 13 - High Level Supply Current vs. Ambient Temperature

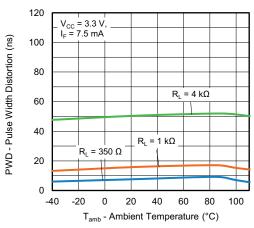


Fig. 14 - Pulse Width Distortion vs. Ambient Temperature

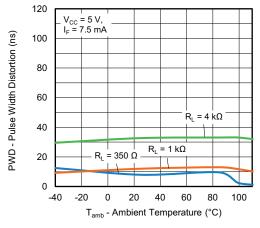


Fig. 15 - Pulse Width Distortion vs. Ambient Temperature



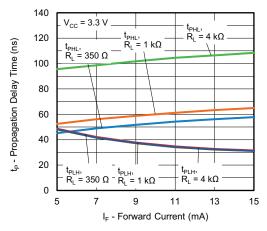


Fig. 16 - Propagation Delay Time vs. Ambient Temperature

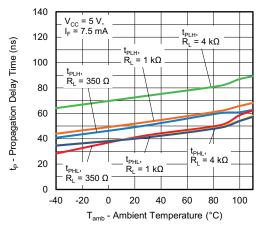


Fig. 17 - Propagation Delay Time vs. Ambient Temperature

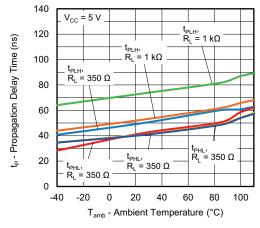


Fig. 18 - Propagation Delay Time vs. Forward Current

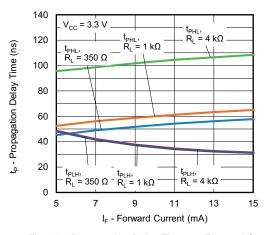


Fig. 19 - Propagation Delay Time vs. Forward Current

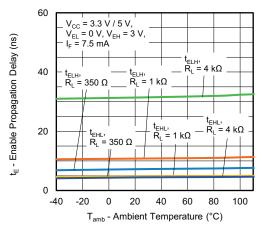
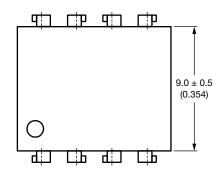


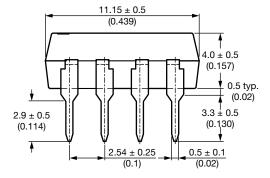
Fig. 20 - Enable Propagation Delay vs. Ambient Temperature



PACKAGE DIMENSIONS (in millimeters)

DIP-8, 400 mil, widebody





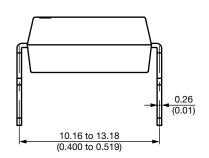


Fig. 21

SMD-8, 400 mil, widebody

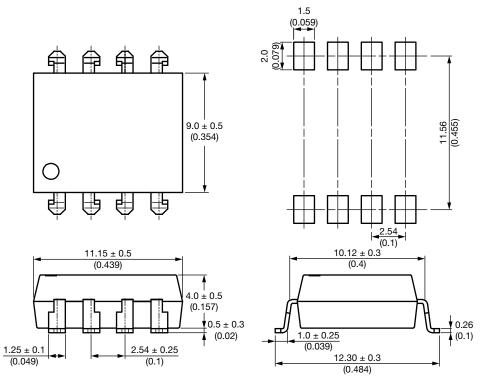


Fig. 22

PACKAGE MARKING



Fig. 23 - Example of VOWH260A



Fig. 24 - Example of VOWH260A-X017T

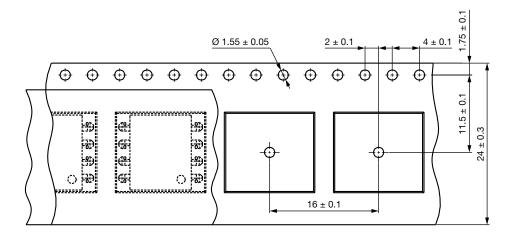
Notes

- "YWW" is the date code marking (Y = year code, WW = week code)
- VDE logo is only marked on VDE option parts
- Tape and reel suffix (T) is not part of the package marking

PACKAGING INFORMATION (in millimeters)

DEVICES PER TUBES					
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX		
DIP-8, 400 mil, widebody	40	30	1200		

SMD-8 Tape



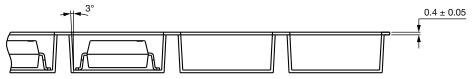


Fig. 25 - Tape and Reel Packaging (750 pieces on reel)

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Reel

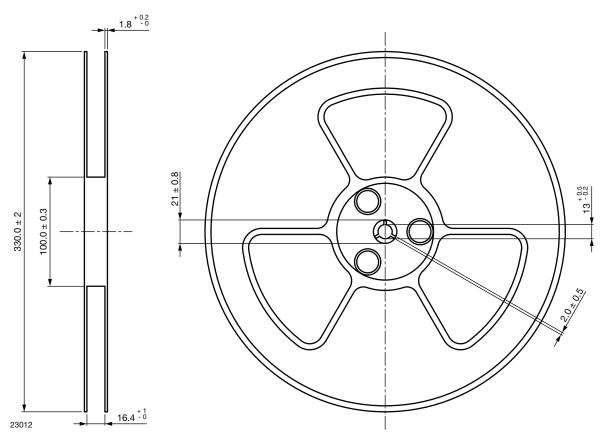


Fig. 26 - Tape and Reel Shipping Medium

SOLDER PROFILES

IR Reflow Soldering (JEDEC® J-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

PROFILE ITEM	CONDITIONS
Preheat	
- Temperature minimum (T _{S min.})	150 °C
- Temperature maximum (T _{S max.})	200 °C
- Time (min. to max.) (t _S)	90 s ± 30 s
Soldering zone	
- Temperature (T _L)	217 °C
- Time (t _L)	60 s
Peak temperature (T _p)	260 °C
Ramp-up rate	3 °C/s max.
Ramp-down rate	3 °C/s to 6 °C/s

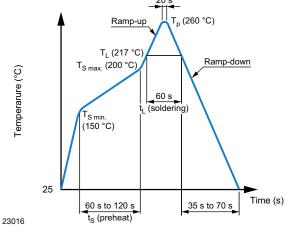


Fig. 27

Wave Soldering (JEDEC JESD22-A111 compliant)

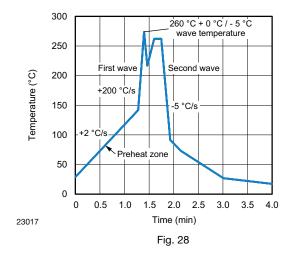
One time soldering is recommended within the condition of temperature.

Temperature: 260 °C + 0 °C / - 5 °C

Time: 10 s

Preheat temperature: 25 °C to 140 °C

Preheat time: 30 s to 80 s



Hand Soldering by Soldering Iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380 °C + 0 °C / - 5 °C

Time: 3 s max.

HANDLING AND STORAGE CONDITIONS

FSD level: HBM class 2 Floor life: unlimited

Conditions: T_{amb} < 30 °C, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020

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